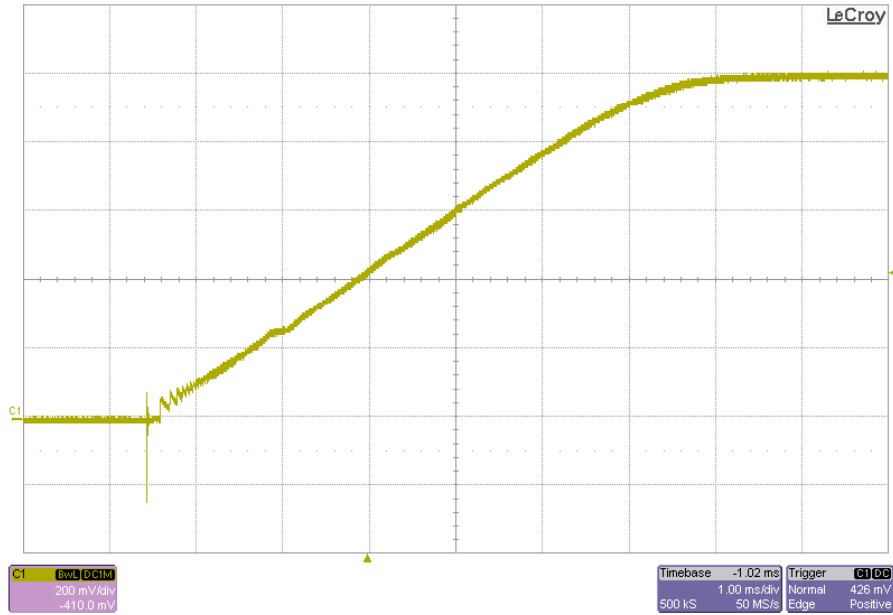


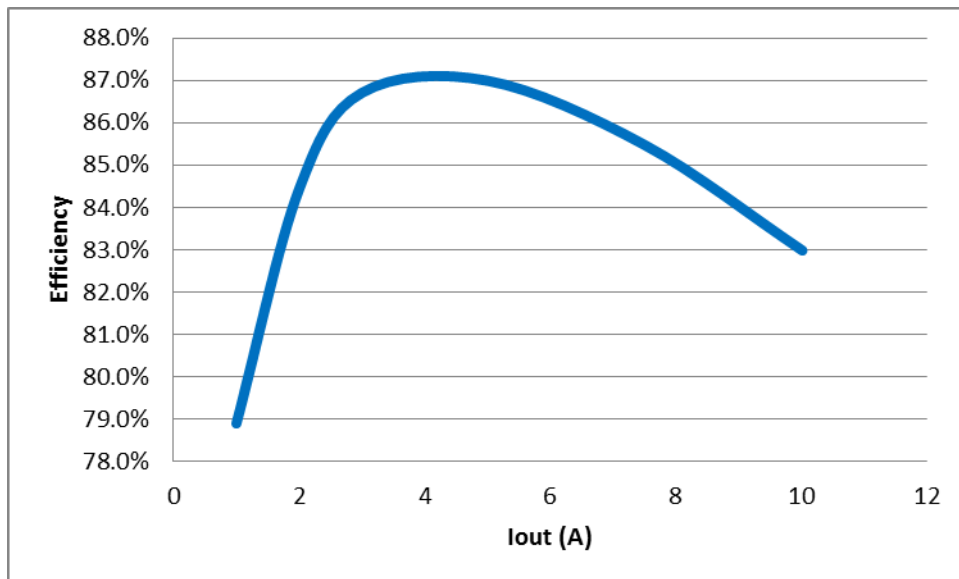
1 Startup

The startup waveform is shown in the figure below. The input voltage was set at 12V, with 1 A load on the output.



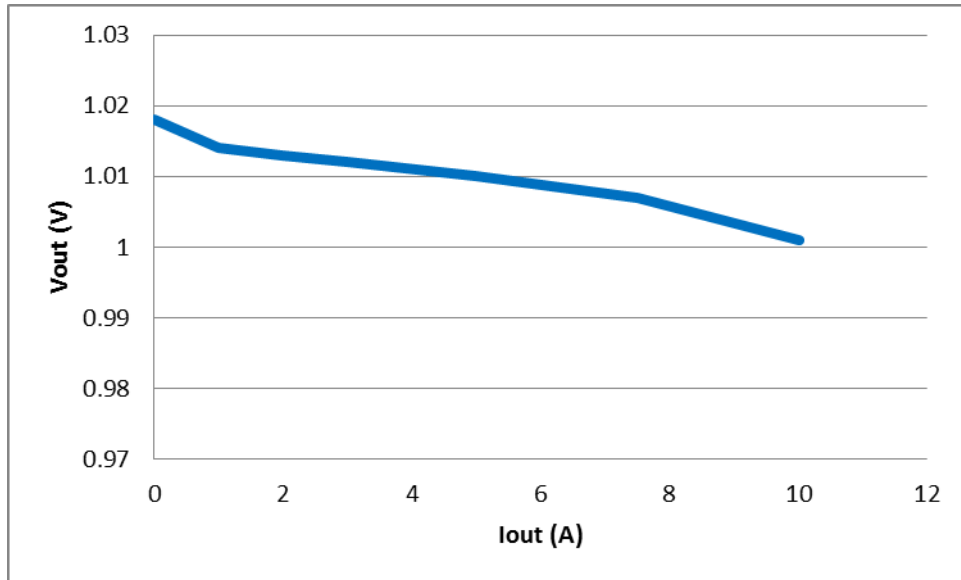
2 Efficiency

The efficiency is shown in the figure below. $V_{in} = 12$ volts, $V_{out} = 1.0$ volts



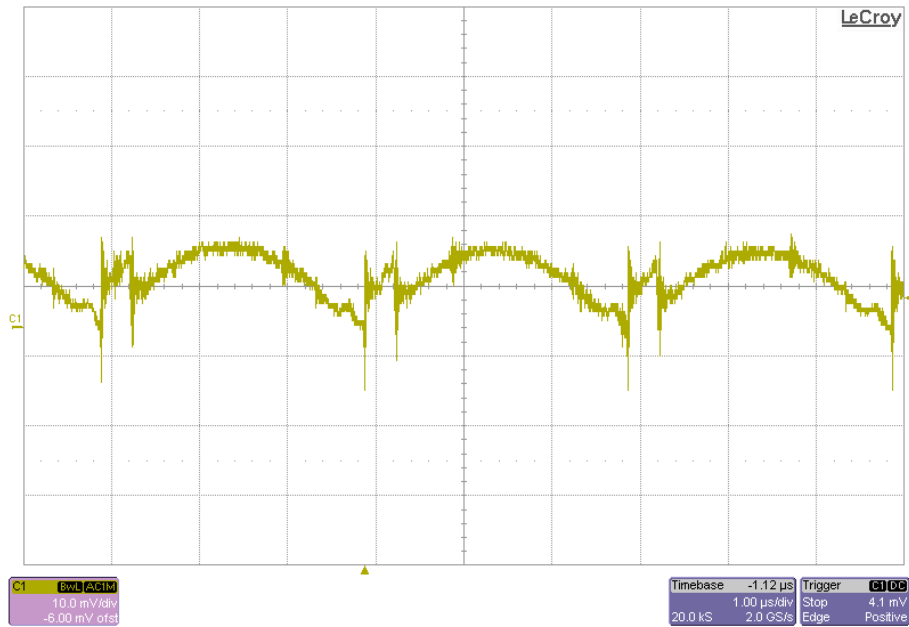
3 Load Regulation

The load regulation of the output is shown in the graph below.



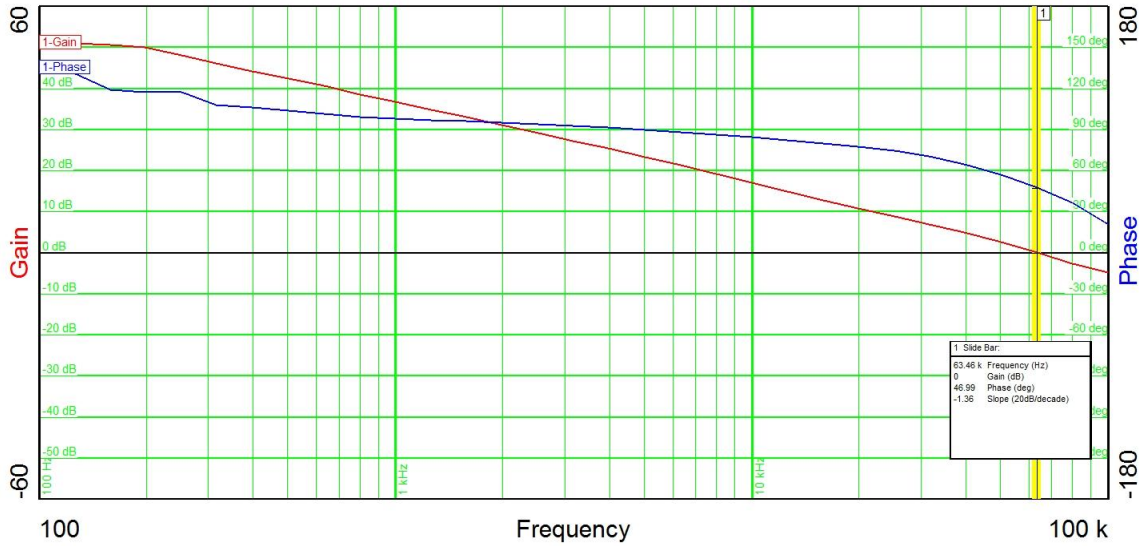
4 Output Ripple Voltage

The output ripple voltage is shown in the figure below. The image was taken with a 10 A load. 10 mV/div Vertical and 2 μ S/div Horizontal.



5 Control Loop Frequency Response

The figure below shows the loop response with a 12V input, and a 1A load.

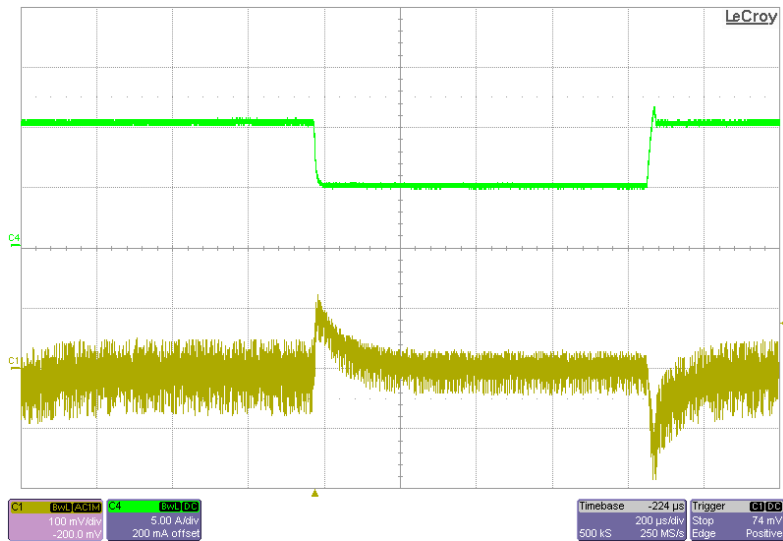


6 Load Transients

The figures below show the response to load transients. The input voltage was set to 12V.

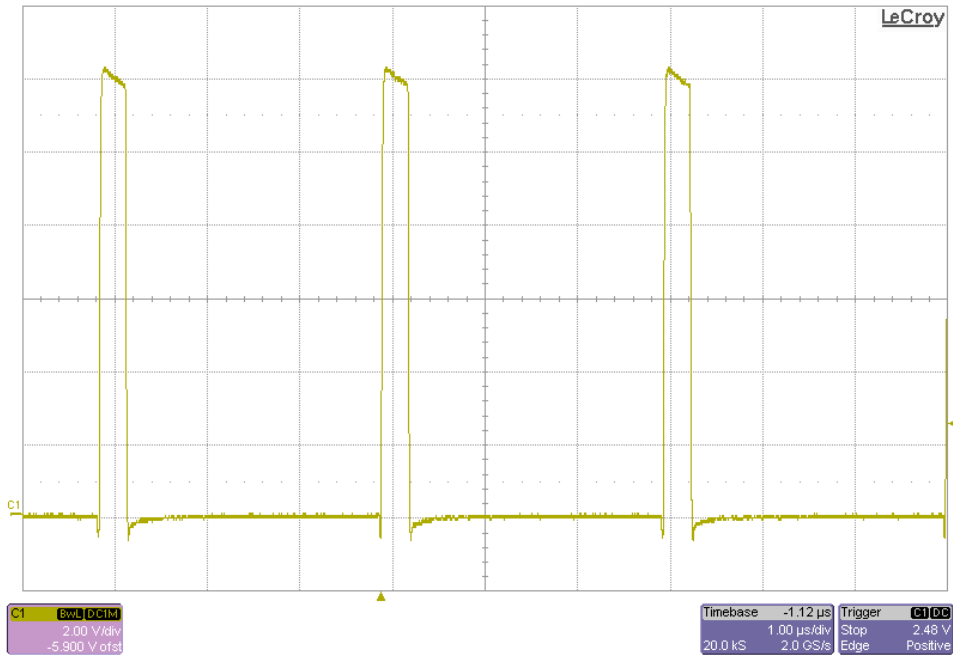
Channel 1 : Vout (AC coupled)

Channel 4 : Load current



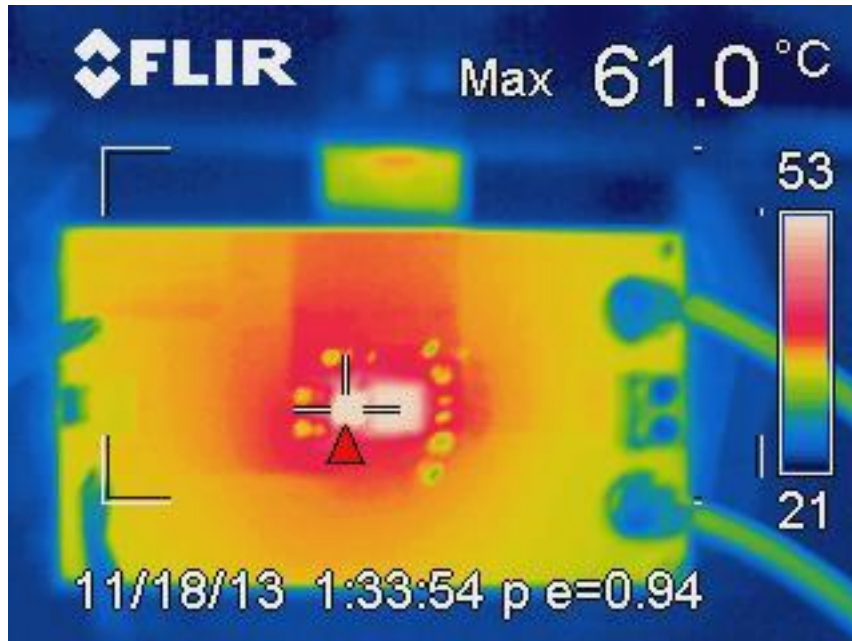
7 Switch Node Waveform

The figure below shows the switch node waveform at 12 volts in and 10 amps out.



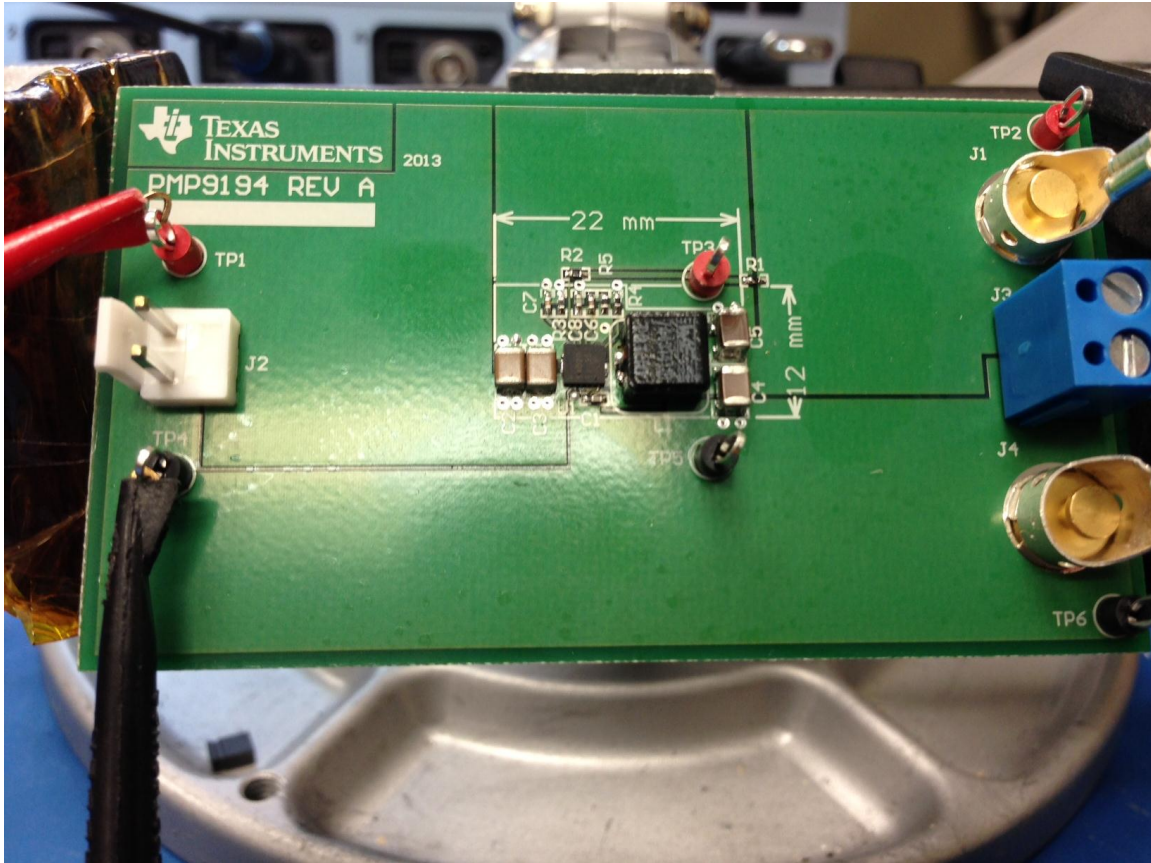
8 Thermal Map

The figure below shows thermal map after 1 hour at 10 amp load and 1 volt in 25 C degree ambient. Max temperature rise was 35 C degrees.



9 Picture

The figure below shows the board in the same orientation as the thermal picture.



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